

Compound Wafer Polishing Pad



NITTA HAAS

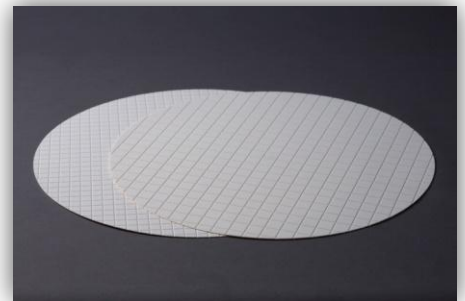
The electrical transfer speeds of compound semiconductors are faster than silicon. In addition, they have an excellent characteristics, including high-speed signal processing and low voltage. As a key technology, they have matured enough to be used widely throughout our life. We have a product lineup that allows advanced and stable polishing performance such as high flatness, low defectivity, and high productivity.

SUBA™ Series

SUBA™ series are felt based pads and designed for high removal rate, better flatness and low defectivity in compound wafers.

Benefit

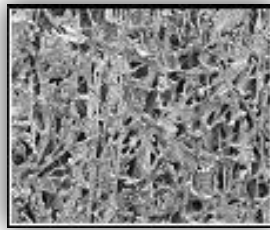
- High removal rate
- Excellent flatness
- Low defectivity



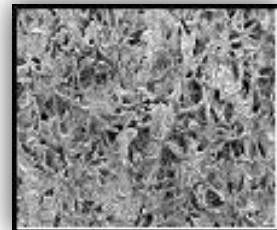
SEM Image



SUBA400



SUBA600



SUBA800

Physical Properties

Product	Thickness (mm)	Hardness (Asker C)	Compressibility (%)
SUBA™ 400	1.27	60	9.4
SUBA™ 400H	1.27	67	7.5
SUBA™ 600	1.27	80	4.2
SUBA™ 800	1.27	83	3.3
SUBA™ 840	1.27	84	2.6
SUBA™ 800M2	1.27	87	2.7

※ SUBA™ is the trademark of Nitta Haas Incorporated.

※ The values such as a physical property indicated, show the standard value. The product specifications are not guaranteed.
The specifications are subject to change for improvement without any notice.